



30V P-CHANNEL ENHANCEMENT MODE MOSFET PowerDI5060-8

Product Summary

BV _{DSS}	R _{DS(ON)}	I _D T _C = +25°C
-30V	$2.6 m\Omega$ @ $V_{GS} = -10V$	-100A
	$3.75 \text{m}\Omega$ @ $V_{GS} = -4.5 \text{V}$	-70A

Description

This new generation MOSFET is designed to minimize $R_{DS(ON)}$ and yet maintain superior switching performance. This device is ideal for use in notebook battery power management and load switch.

Applications

Switch

PowerDI5060-8 (Type K)





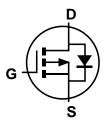


Features

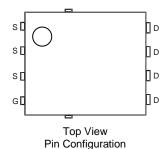
- 100% Unclamped Inductive Switch (UIS) Test in Production
- Thermally Efficient Package-Cooler Running Applications
- High Conversion Efficiency
- Low R_{DS(ON)} Minimizes On State Losses
- <1.1mm Package Profile Ideal for Thin Applications
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: PowerDI[®] 5060-8
- Case Material: Molded Plastic, "Green" Molding Compound;
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Finish Matte Tin Annealed over Copper Leadframe;
 Solderable per MIL-STD-202, Method 208 ³
- Weight: 0.097 grams (Approximate)



Internal Schematic



Ordering Information (Note 4)

Part Number	Case	Packaging
DMP32M6SPS-13	PowerDI5060-8 (Type K)	2,500 / Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information

PowerDI5060-8 (Type K)

D D D D

P32M6SS

YY WW

S S S G

☐ H = Manufacturer's Marking
P32M6SS = Product Type Marking Code
YYWW = Date Code Marking
YY = Last Two Digits of Year (ex: 19 = 2019)
WW = Week Code (01 to 53)

PowerDI is a registered trademark of Diodes Incorporated.



Maximum Ratings (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic				Value	Unit
Drain-Source Voltage			V_{DSS}	-30	V
Gate-Source Voltage			V_{GSS}	±20	V
Continuous Drain Current, V _{GS} = -10V (Note 7) (Package Limited)	Steady State	$T_C = +25$ °C $T_C = +70$ °C	Ι _D	-100 -70	А
Continuous Drain Current, V _{GS} = -10V (Note 6)	t ≤ 10s	$T_A = +25$ °C $T_A = +70$ °C	I _D	-37 -30	Α
Pulsed Drain Current (380µs Pulse, Duty Cycle = 1%)				-400	Α
Maximum Continuous Body Diode Forward Current (Note 6)			Is	-2.7	Α
Pulsed Body Diode Forward Current (380µs Pulse, Duty Cycle = 1%)			I _{SM}	-400	Α
Avalanche Current, L = 0.1mH (Note 8)			I _{AS}	-80	Α
Avalanche Energy, L = 0.1mH (Note 8)			E _{AS}	250	mJ

Thermal Characteristics

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)		P_{D}	1.3	W
Thermal Desistance, Junction to Ambient (Note 5)	Steady State	<u> </u>	98	°C/W
Thermal Resistance, Junction to Ambient (Note 5)	t ≤ 10s	$R_{\theta JA}$	49	
Total Power Dissipation (Note 6)		P_{D}	2.3	W
Thermal Desistance, Junction to Ambient (Note C)	Steady State	1	54	°C/W
Thermal Resistance, Junction to Ambient (Note 6)	t ≤ 10s	$R_{\theta JA}$	27	
Thermal Resistance, Junction to Case (Note 7)		$R_{\theta JC}$	0.9	°C/W
Operating and Storage Temperature Range		$T_{J,}T_{STG}$	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 9)							
Drain-Source Breakdown Voltage	BV _{DSS}	-30	_	_	V	$V_{GS} = 0V, I_{D} = -250\mu A$	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	-1	μΑ	$V_{DS} = -24V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 9)							
Gate Threshold Voltage	V _{GS(TH)}	-1.0	_	-2.5	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
Static Drain-Source On-Resistance	D	_	1.8	2.6	mΩ	$V_{GS} = -10V, I_D = -20A$	
Static Drain-Source On-Resistance	R _{DS(ON)}	_	2.4	3.75	11177	$V_{GS} = -4.5V, I_D = -20A$	
Diode Forward Voltage	V _{SD}	_	-0.6	-1.2	V	$V_{GS} = 0V, I_{S} = -1A$	
DYNAMIC CHARACTERISTICS (Note 10)							
Input Capacitance	Ciss		8594		pF	V 45V V 0V	
Output Capacitance	Coss	_	1491	_	pF	$V_{DS} = -15V, V_{GS} = 0V$ of = 1MHz	
Reverse Transfer Capacitance	C _{rss}	_	874	_	pF		
Gate Resistance	Rg	_	6.38	_	Ω	$V_{DS} = 0V$, $V_{GS} = -15$ mV, $f = 1$ MHz	
Total Gate Charge (V _{GS} = -4.5V)	Qg	_	75	_	nC		
Total Gate Charge (V _{GS} = -10V)	Qg	_	158	_	nC	V 45V L 25A	
Gate-Source Charge	Qgs	_	23.0	_	nC	$V_{DS} = -15V, I_D = -25A$	
Gate-Drain Charge	Q _{qd}	_	25.5	_	nC		
Turn-On Delay Time	t _{D(ON)}	_	6.74	_	ns		
Turn-On Rise Time	t _R	_	5.46	_	ns	$V_{DS} = -15V, V_{GS} = -10V,$	
Turn-Off Delay Time	t _{D(OFF)}	_	227	_	ns	$R_{GS} = 2.7\Omega, I_D = -1A$	
Turn-Off Fall Time	t _F	_	108		ns	1	
Reverse Recovery Time	t _{RR}	_	37.4	_	ns	054 3/4 4004/	
Reverse Recovery Charge	Q _{RR}	_	36.8	_	nC	I _F = -25A, di/dt = 100A/μs	

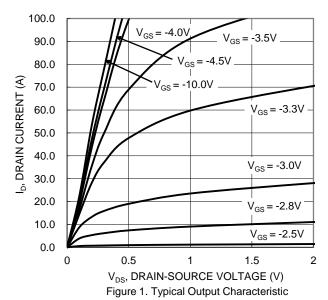
5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
7. Thermal resistance from junction to soldering point (on the exposed drain pad).

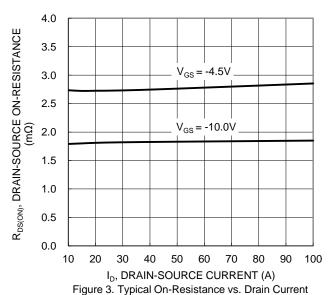
- 8. I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep T_J = +25°C.
- 9. Short duration pulse test used to minimize self-heating effect.
- 10. Guaranteed by design. Not subject to product testing.

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DMP32M6SPS





and Gate Voltage

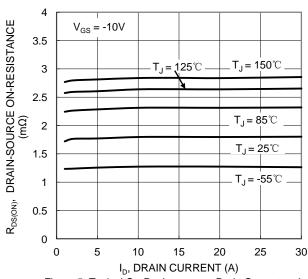


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

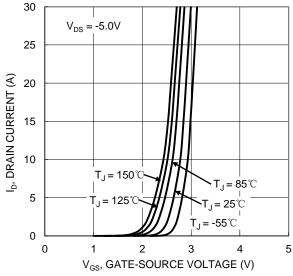
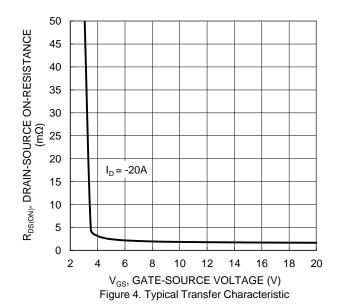


Figure 2. Typical Transfer Characteristic



2 R_{DS(ON)}, DRAIN-SOURCE ON-RESISTANCE 1.8 $V_{GS} = -10V, I_D = -20A$ 1.6 (NORMALIZED) 1.2 1 $V_{GS} = -4.5V, I_{D} = -20A$ 8.0 0.6 0.4 -50 -25 0 25 50 75 100 125 150 T_J , JUNCTION TEMPERATURE ($^{\circ}$)

Figure 6. On-Resistance Variation with Junction Temperature



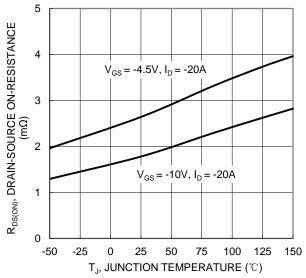
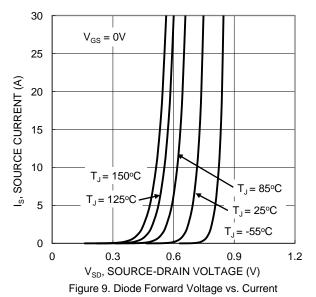


Figure 7. On-Resistance Variation with Junction Temperature



10 8 6 $V_{GS}(V)$ 4 $V_{DS} = -15V, I_{D} = -25A$ 2 0 60 80 20 40 100 120 140 160 $Q_q(nC)$

Figure 11. Gate Charge

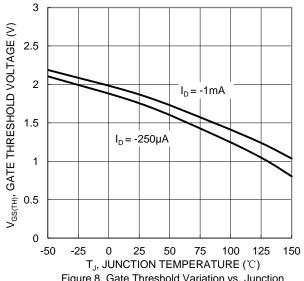
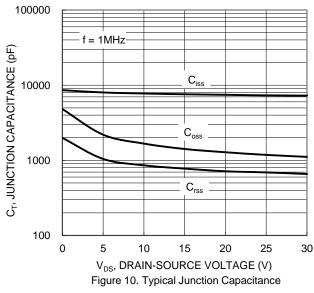


Figure 8. Gate Threshold Variation vs. Junction Temperature



1000 100 ID, DRAIN CURRENT (A) 10 $T_{J(Max)} = 150^{\circ}C$ = 100 ms $T_C = 25^{\circ}C$ Single Pulse DUT on Infinite Heatsink $V_{GS} = -10V$ 0.1 0.1 10 100 V_{DS}, DRAIN-SOURCE VOLTAGE (V) Figure 12. SOA, Safe Operation Area



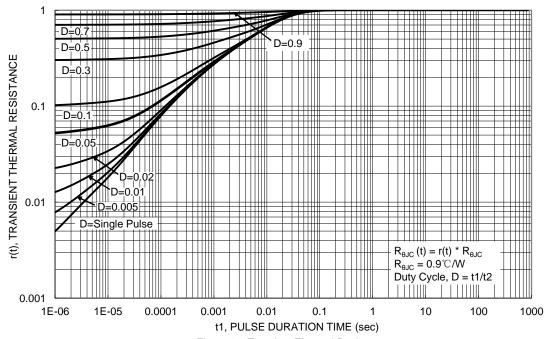


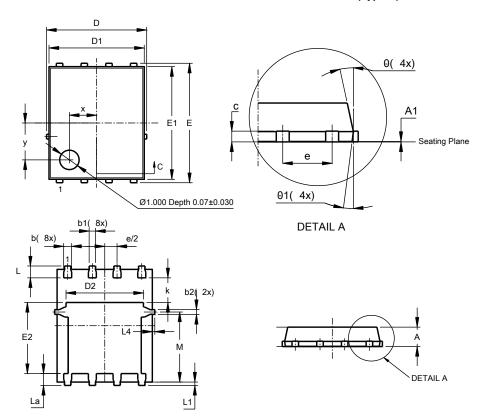
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI5060-8 (Type K)

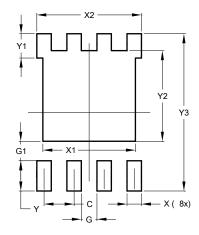


PowerDI5060-8 (Type K)						
Dim	Min	Max	Тур			
Α	0.90	1.10	1.00			
A 1	0	0.05	0.02			
b	0.33	0.51	0.41			
b1	0.300	0.366	0.333			
b2	0.20	0.35	0.25			
С	0.23	0.33	0.277			
D	5	.15 BS0	2			
D1	4.85	4.95	4.90			
D2	-	-	3.98			
E	6	.15 BS0	2			
E1	5.75	5.85	5.80			
E2	3.56	3.725	3.66			
е	1	.27BSC	;			
k	-	-	1.27			
٦	0.51	0.71	0.61			
La	0.51	0.675	0.61			
L1	0.05	0.20	0.175			
L4	-	-	0.125			
M	3.50	3.71	3.605			
Х	-	-	1.400			
у	-	-	1.900			
θ	10°	12°	11°			
θ1	6°	8°	7°			
All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI5060-8 (Type K)



Dimensions	Value			
Dillicitations	(in mm)			
C	1.270			
G	0.660			
G1	0.820			
Х	0.610			
X1	3.910			
X2	4.420			
Y	1.270			
Y1	1.020			
Y2	3.810			
Y3	6.610			



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